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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/713,117	11/17/2003	Woon-Kyung Lee	SEC.697D	9793
75	90 04/19/2005		EXAMINER	
VOLENTINE FRANCOS, PLLC			TRINH, MICHAEL MANH	
SUITE 150 12200 SUNRIS	E VALLEY DRIVE		ART UNIT	PAPER NUMBER
RESTON, VA	20191		2822	
			DATE MAILED: 04/19/2003	5

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)				
Office Action Summer	10/713,117	LEE ET AL.	(lug)			
Office Action Summary	Examiner	Art Unit				
	Michael Trinh	2822				
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	correspondence ad	dress			
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	side (a). In no event, however, may a reply be ting within the statutory minimum of thirty (30) day ill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nely filed s will be considered timely the mailing date of this co D (35 U.S.C. § 133).				
Status						
1) Responsive to communication(s) filed on 17 No.	ovember 2003.					
	action is non-final.					
3) Since this application is in condition for allowant closed in accordance with the practice under E	ice except for formal matters, pro		e merits is			
Disposition of Claims						
4) ☐ Claim(s) 11-24 is/are pending in the application 4a) Of the above claim(s) is/are withdraw 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 11-24 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction and/or	vn from consideration.					
Application Papers						
9) The specification is objected to by the Examiner	r.					
10)☐ The drawing(s) filed on is/are: a)☐ accepted or b)☐ objected to by the Examiner.						
Applicant may not request that any objection to the o	• • •	` '				
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).  1) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.						
Priority under 35 U.S.C. § 119						
<ul> <li>12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).</li> <li>a) All b) Some * c) None of:</li> <li>1. Certified copies of the priority documents have been received.</li> <li>2. Certified copies of the priority documents have been received in Application No. 09/566,916.</li> <li>3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).</li> <li>* See the attached detailed Office action for a list of the certified copies not received.</li> </ul>						
Attachment(s)  I) Notice of References Cited (PTO-892)	4) Interview Summary					
Notice of Draftsperson's Patent Drawing Review (PTO-948)  Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)	Paper No(s)/Mail Da 5) Notice of Informal P		)-152)			
Paper No(s)/Mail Date <u>11-17-03</u> .	6)					

Application/Control Number: 10/713,117 Page 2

Art Unit: 2822

## **DETAILED ACTION**

\*\*\* This office action is in response to filling of the application on November 17, 2003. Claims 1-10 were canceled. Claims 11-24 are current pending.

## Claim Rejections - 35 USC § 112

- 1. Claims 11-17,19-20, and 21-24 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.
- \*\* Claim 11 is indefinite and incomplete, since it depends on canceled claim 1.

  Other dependent claims are rejected as depending on rejected indefinite base claim.
- \*\* Claim 21 (lines 13-14) is unclear for using of different terms for the same layer. It is suggested the term "a second silicon layer" (at lines 13-14 of claims 18 and 21) be amended as -- a second polysilicon layer--, since "the first and second polysilicon layers" is already mentioned at line 15, claim 21 (claims 23 and 24 also recite "polysilicon").
- \*\* Similarly, Claim 18 (lines 13-14) is unclear for using of different terms for the same layer. It is suggested the term "a second silicon layer" be amended as --a second polysilicon layer--, since "the first and second polysilicon layers" is already mentioned at line 15, claim 21.

## Allowable Subject Matter

- 2. Claims 18, 21-24 would be allowable if rewritten or amended to overcome the rejection(s) under 35 U.S.C. 112, 2nd paragraph, as suggestion and set forth in this Office action.
- The following is a statement of reasons for the indication of allowable subject matter. The references including Hasegawa (5,891,780), Sheng (5,585,297), Chung (5,891,779), of record, alone or in combination, do not anticipatively disclose each and every aspect of the claimed method, or fairly make a prima facie obvious case of the claimed method, in combination with other processing claimed limitations as recited in base claims, the inclusion of, as in claim 21, forming a photoresist patterns on the first polysilicon layer formed on the gate insulation layer, which entirely cover a peripheral circuit region but are patterned in a cell array region to expose regions which are to become buried impurity regions; performing ion

Art Unit: 2822

implantation using the photoresist patterns as a mask so as to form buried impurity regions near the surface of the semiconductor substrate, wherein the buried impurity regions are parallel, separated from each other by a predetermined interval and extend in the same direction; removing the photoresist patterns, and sequentially stacking a second polysilicon layer and a metal silicide layer on the first polysilicon layer; and sequentially etching the first and second polysilicon layers and the metal silicide layer so as to form word lines, wherein the word lines are parallel, separated from each other by a predetermined interval and extend in the perpendicular direction to the buried impurity diffusion region.

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Michael M. Trinh whose telephone number is (571) 272-1847. The examiner can normally be reached on M-F: 8:30 Am to 5:00 Pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on (571) 272-1852. The fax phone number is (703) 872-9306.

Any inquiry of a general nature or relating to the status of this application should be directed to the receptionist whose telephone number is (703) 308-0956. Oacs-9

Michael Trinh Primary Examiner